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**SATOH et al.**(10) **Pub. No.: US 2023/0232722 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **VIBRATION DEVICE**(71) Applicant: **TDK CORPORATION**, Tokyo (JP)(72) Inventors: **Akira SATOH**, Tokyo (JP); **Kaoru KIJIMA**, Tokyo (JP)(73) Assignee: **TDK CORPORATION**, Tokyo (JP)(21) Appl. No.: **18/079,292**(22) Filed: **Dec. 12, 2022**(30) **Foreign Application Priority Data**

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(57)

**ABSTRACT**

A vibration device includes: a piezoelectric unit including a piezoelectric element; a housing that holds the piezoelectric unit; a wiring member electrically connected to the piezoelectric unit; and a joining member that joins the housing to an external device. The housing includes a bottom surface portion to which the piezoelectric unit is fixed, and a side surface portion standing at an edge portion of the bottom surface portion. The side surface portion has a first surface formed on a top portion of the side surface portion, and a second surface that is one step lowered from the first surface by a cutout portion formed in the top portion. The joining member extends along the first surface to bridge over the cutout portion. The wiring member is joined to the joining member at a position of the first surface, and passes through the cutout portion in a state where the wiring member is not joined to the second surface.

